产品介绍 Product Introduction

N型大尺寸超薄单晶硅片

N-type large-sized ultra-thin monocrystalline silicon wafer

薄如纸，吸太阳精华

Paper-thin, absorbing sun-essence

技术亮点 Technical highlights

- **尺寸：210*182.2mm，厚度：130μm**
  Size: 191.6*182.2mm, thickness: 130μm

- **超高表面平整度控制技术，总厚度偏差均值≤8μm**
  Ultra-high surface flatness control technology, average thickness deviation ≤8μm

- **高效智能化切割总体解决方案，表面线痕均值≤8μm**
  Efficient and intelligent slicing overall solution, average surface line mark value ≤8μm

- **超细线快速切割，更低损伤，更低热应力**
  Cutting with finner wire diameter and higher speed，that results in minimal damage and reduced thermal stress

技术参数 Technical Data

- **厚度：130±10μm**
  Thickness: 130±10μm

- **无划痕/缺口/孔洞/脏污**
  No scratches/gaps/holes/dirt

- **边长：210*182.2±0.25mm**
  Side length: 210*182.2±0.25mm

- **氧含量≤11ppma**
  Oxygen content: ≤11ppma